

AMENDMENTS TO THE CLAIMS:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-8. (Cancelled)

9. (New) An arrangement for a junction between a microstripline and a waveguide, comprising:

a microstripline which is fitted on an upper face of a dielectric substrate;

a waveguide which is fitted on the upper face of the substrate and has an opening on at least one end surface and has a structure which is in the form of a step or steps in the area of the opening on one side wall and is conductively connected in at least one part to the microstripline, and wherein one side wall of the waveguide is a metallized layer formed on the substrate;

a cutout which is formed in the metallized layer and into which the microstripline projects;

rear-face metallization which is formed on a rear face of the substrate; and

electrically conductive via holes between the metallized layer on the upper face of the substrate and the rear-face metallization, which surround the cutout.

10. (New) The arrangement as claimed in claim 9, wherein the waveguide is a surface mounted device.

11. (New) The arrangement as claimed in claim 9, wherein the structure which is in the form of a step or steps is formed on a side wall of the waveguide which is opposite the cutout.

12. (New) The arrangement as claimed in claim 10, wherein the structure which is in the form of a step or steps is formed on a side wall of the waveguide which is opposite the cutout.

13. (New) The arrangement as claimed in claim 9, wherein a distance between the via holes is chosen such that the radiated emission of the electromagnetic wave in the useful frequency range through the intermediate spaces is small, and the operation of the junction is thus not adversely affected by increased losses or undesirable couplings.

14. (New) The arrangement as claimed in claim 13, wherein the via holes run in a number of rows which are arranged parallel to one another.

15. (New) The arrangement as claimed in claim 9, wherein the substrate has a waveguide opening in the area of the metallized layer on the upper face of the substrate.

16. (New) The arrangement as claimed in claim 11, wherein the substrate has a waveguide opening in the area of the metallized layer on the upper face of the substrate.

17. (New) The arrangement as claimed in claim 14, wherein an inner surface of the waveguide opening is electrically conductive.

18. (New) The arrangement as claimed in claim 14, wherein a side wall of the waveguide which is opposite the upper face of the substrate has a structure, which is in the form of a step or steps, in the area of the waveguide opening.

19. (New) The arrangement as claimed in claim 15, wherein a side wall of the waveguide which is opposite the upper face of the substrate has a structure, which is in the form of a step or steps, in the area of the waveguide opening.